

PRODUCT NUMBER

77773-YXXLF

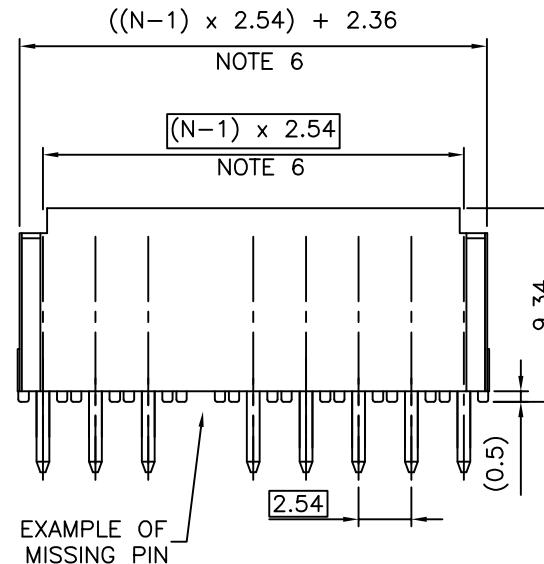
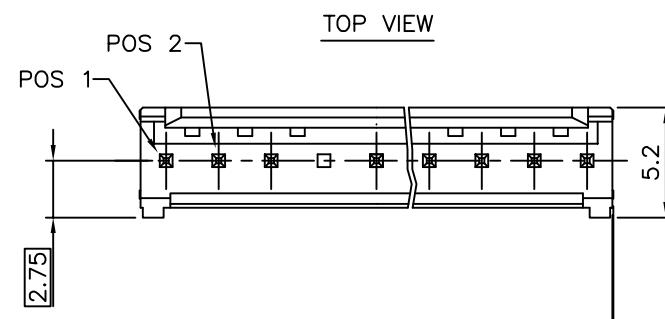
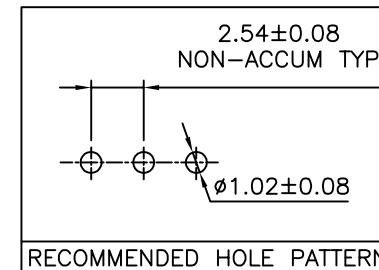
PLATING

3=0.76 μ m GOLD/GXT ON CONTACT AREA
2 μ m MIN MATTE TIN ON TAIL
4=2 μ m MIN MATTE TIN FULL PLATED
1.27 μ m Ni MIN UNDERPLATING

STYLE	SIZE	OMIT PIN POSITION FROM TOP VIEW	
		2	8
01	1x09		
02	1x35	4;5;6;7;8;12;13;14;15;16;20;21;22;23;24;28;32	
03	1x21	2;4;6;8;10;12;14;16;18;20;21	
04	1x21	1;2;4;6;8;10;12;14;16;18;20	
05	1x10		8
06	1x06		1
07	1x08		7
08	1x04		2
09	1x04		3
12	1x21	2;4;6;8;10;12;14;16;18;20	
13	1x05		2;4
14	1x03		2

NOTES:

1. BODY MATERIAL: POLYESTER 30% GLASSFILLED COLOR BLUE, FLAME RETARDANT PER UL-94 VO.
2. CONTACT MATERIAL: PHOSPHOR BRONZE.
3. 15N MIN PIN RETENTION IN EITHER DIRECTION
4. 0.6 MAX PROTRUSION PERMITTED AT 4 PLACES
5. PACKAGING :
 - POLYBAGS FROM 02 TO 06 POSITIONS
 - TUBE FROM 07 TO 36 POSITIONS
6. TO DETERMINE DIMENSIONS :
N = NUMBER OF POSITIONS PER ROW
EXAMPLE : 8 POS N x 2.54 = 20.32mm
7. RoHS COMPATIBLE PRODUCT SPECIFICATIONS
 - a - PLATING:
 - "LF" MEANS THE PRODUCT IS LEAD-FREE, 2 μ m MINIMUM MATTE TIN OVER 1.27 μ m MINIMUM NICKEL UNDERPLATE.
 - b - MANUFACTURING PROCESS COMPATIBILITY
 - THE HOUSING WILL WITHSTAND EXPOSURE TO 245°C \pm 5°C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.
 - c - LABELING:
 - MEETS PACKAGING SPECS AS PER GS-14-920
 - d - LEGAL STATEMENT: SEE GS-47-0004



mat'l. code		surface		tolerance		projection	product family
ltr	ecn no	dr	date	tolerances unless otherwise specified			
V	F08-0147	Y0V	08.04.14	angles	.X \pm 0.3		
W	F09-0026	LMU	09.03.11	linear	.XX \pm 0.15		
X	B-19285	AMA	14.11.03		.XXX \pm 0.05	scale 4:1	
Y	F-21810	AMA	15.06.19	dr	COMPAGNON J	95.03.06	
				engr	PHAMVAN JM	95.03.06	
T	F05-0244	JCO	05.09.06	chr	JMC	95.04.04	
U	F06-0228	LMU	06.07.11	dppd	JMP	95.04.04	
sheet	revision						
index	sheet						

dwg no sheet 1 of 1 size
77773 A3
type CUSTOMER Drawing

FCI